

WHAT IS CLAIMED IS:

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1. A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are welded by fusion to join connection terminals provided on said mounting substrate, said mounting method comprising the steps of:

arranging a flux paste on said mounting substrate, said flux paste including a base flux and metal grains having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said flux paste and said electronic part when said electronic part is mounted on said mounting substrate; and

sealing a resin in the space formed between said electronic part and said mounting substrate after said projection electrodes are joined to said connection terminals.

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2. The method as claimed in claim 1, wherein the diameters of said metal grains are defined to be more than a tolerance of diameters of said projection electrodes and less than one third the diameter of said projection electrodes, and

said flux paste includes said metal grains more than one percent and less than twenty percent by volume ratio.

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3. The method as claimed in claim 1,  
wherein said flux paste is arranged on an area having  
said connection terminals of said mounting substrate  
5 by a thickness being more than the diameters of said  
metal grains and less than half the diameters of said  
projection electrodes.

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4. The method as claimed in claim 1,  
wherein a base flux of said flux paste includes a  
resin used to seal the space as a main constituent.

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5. The method as claimed in claim 1,  
20 wherein a base flux of said flux paste includes a  
resin, which is used to seal the space and filler is  
eliminated from, as a main constituent.

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6. The method as claimed in claim 1,  
wherein:

30 said projection electrodes have a  
spherical shape, and

said metal grains have a shape having a  
smooth surface so as to be movable when said  
projection electrodes are pressed to said connection  
terminals.

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7. A method for mounting an electronic part on a mounting substrate in that projection electrodes provided on said electronic part are  
5 welded by fusion to join connection terminals provided on said mounting substrate, said mounting method comprising the steps of:  
arranging a flux paste on said projection electrodes, said flux paste including metal grains  
10 having diameters smaller than diameters of said projection electrodes and having a thickness so as to form a space between said electronic part and said flux paste when said electronic part is mounted on said mounting substrate;  
15 joining said projection electrodes to said connection part by mounting said electronic part on said mounting substrate and conducting a heating process; and  
sealing a resin in said space formed  
20 between said electronic part and said mounting substrate after said projection electrodes are joined to said connection terminals.

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8. The method as claimed in claim 7, wherein the diameters of said metal grains are defined to be more than a tolerance of the diameters  
30 of said projection electrodes and less than one third the diameter of said projection electrodes, and  
said flux paste includes said metal grains more than one percent and less than twenty percent by volume ratio.

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9. The method as claimed in claim 7,  
wherein a base flux of said flux paste includes a  
resin used to seal the space as a main constituent.

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10. The method as claimed in claim 7,  
10 wherein a base flux of said flux paste includes a  
resin, which is used to seal the space and filler is  
eliminated from, as a main constituent.

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11. The method as claimed in claim 7,  
wherein:

20 said projection electrodes have a  
spherical shape, and

said metal grains have a shape having a  
smooth surface so as to be capable of being pushed  
outward when said projection electrodes are pressed  
to said connection terminals.

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12. A paste material used to weld by  
30 fusion projection electrodes provided on an  
electronic part to connection terminals provided on a  
mounting substrate, said paste material comprising:

metal grains; and

a base flux,

35 wherein diameters of said metal grains are  
defined to be more than a tolerance of diameters of  
said projection electrodes and less than one third

the diameter of said projection electrodes, and  
said metal grains are included more than  
one percent and less than twenty percent by volume  
ratio.